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Serial Number: 10763685

1.) See <u>attached</u> printout of inventors listed in PALM

2.) See <u>attached</u> EAST Inventor Search Printout shows Inventor search terms



PALM INTRANET

Day: Friday Date: 10/20/2006 Time: 10:42:16

Inventor Information for 10/763685

Inventor Name	City	State/Country			
MOON, BYUNG JIN	PALDAL-GU	KOREA, REPUBLIC OF			
Appln Info Contents Petition Info	Atty/Agent Info	Continuity/Reexam Foreign Data Invento			
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US	20060824	Pattern detection for	702/117		Whitefield;
20060190207	2000002-1	integrated circuit	,02,11,		Bruce J. et al.
A1		substrates			
	20060220		435/6	435/7.1	McMillan;
US	20060330	Multiple bead	433/0	433/7.1	William A. et
20060068399		reagent system for			
A1		protein based assays			al.
		with optimized			
		matrices			
US	20060316	Memory device	365/205		Park; Ki-Won
20060056252		having open bit line			et al.
A1		cell structure using			
		burn-in testing			
		scheme and method			
		therefor			
US	20060209	MEMORY DEVICE	365/230.06	365/189.07;	Shin; Dong-
20060028900	20000209	EMPLOYING	303/230:00	365/200;	Hak et al.
		OPEN BIT LINE		365/203	Trunc or un.
A1		ARCHITECTURE		303/203	
		FOR PROVIDING			
		IDENTICAL DATA			.
		TOPOLOGY ON			
		REPAIRED			
		MEMORY CELL			
		BLOCK AND	Į.		
		METHOD			
		THEREOF			
US	20060105	Redundancy	365/200		Nam; Jeong-
20060002204		program circuit and			Sik et al.
A1		methods thereof			
US	20050623	Method of dispersing	427/221		Jung, Han
20050136181	20030023	and coating additive			Seong et al.
		on dielectric ceramic			
A1 ·		powder			
TIC	20050421	Synthetic resin bag	383/116	383/105;	Moon, Byung
US	20030421		363/110	383/103,	Jin
20050084185		for grain or feed		363/11/	J111 .
Al			12516	425/192	Maan Draing
US	20050331	Lyophilized beads	435/6	435/182;	Moon, Byung
20050069898		containing mannitol		435/91.2	Sook et al.
Al			100000		3.6
US	20050324	Optical dispersion	330/308		Mayampurath,
20050062543		correction in	ŀ		Balagopal et
A1		transimpedance			al.
		amplifiers			
US	20041230	Method for	216/24		Kim, Dong
20040262259		manufacturing			Joon et al.
Al		semiconductor laser			
4 * *			.1		

		device			
US 20040226681 -A1	20041118	Apparatus for manufacturing magnesium-alloy plate by wheel-band continuous casting, and manufacturing method thereof	164/482	164/434; 164/439; 164/488	You, Bong- Sun et al.
US 20040198024 A1	20041007	Method for cutting semiconductor wafer using laser scribing process	438/463		Yoon, Jeong Goo et al.
US 20040101859 A1	20040527	Compositions, methods and kits for polynucleotide amplification reactions and microfluidic devices	435/6	435/91.2; 516/144	Moon, Byung Sook et al.
US 20030076702 A1	20030424-	Semiconductor memory device having first and second memory architecture and memory system using the same	365/51		Kyung, Kye- Hyun et al.
US 20020181310 A1	20021205	Semiconductor memory device internal voltage generator and internal voltage generating method	365/226		Park, Duk-Ha et al.
US 20020021614 A1	20020221	SEMICONDUCTOR MEMORY DEVICE HAVING COLUMN REDUNDANCY SCHEME TO IMPROVE REDUNDANCY EFFICIENCY	365/230.03		Kim, Su-a et al.
US 20020005841 A1	20020117	Transmission method, receiving method, transmitter and receiver of digital video data	345/204	**	Jung, Wonseok et al.
US 20020005606	20020117	Apparatus for manufacturing solder	266/202	222/594	Lee, Jin- Hyung et al.

A 1	1	halla			
A1	20060411	balls	265/200	265/100	Shin: Dong
US 7027339	20060411	Memory device	365/200	365/190	Shin; Dong- Hak et al.
B2		employing open bit			Hak et al.
		line architecture for		,	
		providing identical			
		data topology on			
		repaired memory cell			
		block and method			
		thereof			
US 6762948	20040713	Semiconductor	365/51	365/230.03	Kyun; Kye-
B2		memory device			hyun et al.
•		having first and			
		second memory			
		architecture and			ļ
		memory system			
		using the same			
US 6636451	20031021	Semiconductor	365/226	327/530;	Park; Duk-ha
B2		memory device	· ·	327/538;	et al.
		internal voltage		365/189.07;	
		generator and		365/189.09	
•		internal voltage			
		generating method		• .	
US 6569378	20030527	Apparatus for	266/202	222/594;	Lee; Jin-
B2		manufacturing solder		228/262	Hyung et al.
		balls			
US 6523122	20030218	Computer system for	713/300	713/320;	Moon;
B1		displaying system		713/324	Byung-Do
		state information	•		
		including advanced			
•		configuration and			
		power interface			
		states on a second			
		display			
US 6414896	20020702	Semiconductor	365/230.03	365/200	Kim; Su-a et
B1		memory device			.al.
	-	having column			
•		redundancy scheme			
		to improve			
		redundancy			
		efficiency			
US 6366155	20020402	Reference voltage	327/530	327/538	Moon;
B1		generators and			Byung-sick et
		methods including			al.
		supplementary	:		
		current generation,			
		and integrated			
		- International	L		1

		circuits including the			
US 6362995 B1	20020326	Arrangements of interface logic, memory core, data shift and pad blocks for integrated circuit memory devices	365/51	365/194; 365/220; 365/221; 365/230.03; 365/233; 365/63	Moon; Byung-mo et al.
US 6326833 B1	20011204	Highly effective charge pump employing NMOS transistors	327/536		Moon; Byung-sick
US 6312498 B1	20011106	Method of manufacturing solder balls	75/335	222/593; 222/594; 266/236; 75/331; 75/953	Lee; Jin- Hyung et al.
US 6304500 B1	20011016	Integrated circuit memory devices having data input and output lines extending in the column direction, and circuits and methods for repairing faulty cells	365/200	365/230.03; 365/63	Kyung; Kyehyun et al.
US 6293888 B1	20010925	Wide ratio coverage continuously variable transmission	475/210		Moon; Byung Il
US 6261198 B1	20010717	Continuously variable transmission	475/36		Moon; Byung Il et al.
US 6225379 B1	20010501	Epoxy resin composition for bonding semiconductor chips	523/457	257/E23.04; 523/458	Kwak; Jae- Sung et al.
US 6219298 B1	20010417	High-speed address decoders and related address decoding methods	365/230.06	365/193	Hur; Nak-won et al.
US 6163498 A	20001219	Methods and systems for column line selection in a memory device	365/230.06	365/189.05; 365/194	Moon; Byung-sick
US 6151263 A	20001121	Integrated circuit memory devices having data input	365/230.03	365/63	Kyung; Kye- hyun et al.

		and output lines extending along the column direction			
US 6078536 A	20000620	Packet type integrated circuit memory devices having pins assigned direct test mode and associated methods	365/201	365/230.06	Moon; Byung-sick et al.
US 5881114 A	19990309	Error detecting circuit of a system time clock for an MPEG system decoder	375/376	370/253; 375/359; 375/368	Moon; Byung-Joon
US 5789992 A	19980804	Method and apparatus for generating digital pulse width modulated signal using multiplied component and data signals	332/109	375/238	Moon; Byung-Joon
US 5666458 A	19970909	Reproduction error correction circuit for a video reproduction system, and the method for operating it	386/2	386/20; 386/41; 386/47; 386/90	Moon; Byung-joon et al.
US 5587804 A	19961224	Reproduction error correction circuit for a video reproduction system & the method for operating it	386/2	386/20; 386/47; 386/90	Moon; Byung-Joon et al.
US D331937 S	19921222	Film changing bag	D16/237	396/590; D16/246	Moon; Byungmoon
US 4985721 A	19910115	Film change bag	396/591	190/107; 190/127; 383/119; 396/590	Moon; Byungmoon